



產品承認書

Product Approval Sheet

一.基本內容(INFORMATION)

客戶名稱(Customer Name) :

產品型號(Product Number) : BZ-HZS32B-P-S

料號信息(PN Information) :

客戶料號	參數要求				
	亮度 (mcd)	Φ V(Lm)	CCT(K)	電壓 (V)	CRI (Ra)
	--	Min:160	5000~6300	Max: 4.2	--

二.供應商確認欄(SUPPLIER)

核准(Approved/Date)	審核(Check/Date)	製作(Prepared/Date)
張孝嚴 2016-9-19	張喜光 2016-9-19	熊燦芬 2016-9-19

三.客戶批准欄(CUSTOMER)

產品承認書批准處理：同意 拒絕 其它_____

核准(Approved/Date)	審核(Check/Date)	研發/工程(R&D Dept/Date)

說明：請將已簽副本回覆我司

Please return to us one copy "PRODUCT ACKNOWLEDGEMENT SHEET" with your approved signatures!

佰鴻工業股份有限公司

BRIGHT LED ELECTRONICS CORP.

台北縣板橋市和平路 19 號 3 樓

3F., No. 19, Ho Ping Road, Pan Chiao City,
Taipei, Taiwan, R. O. C.

Tel: 886-2-29591090

Fax: 886-2-29547006/29558809

www.brtled.com

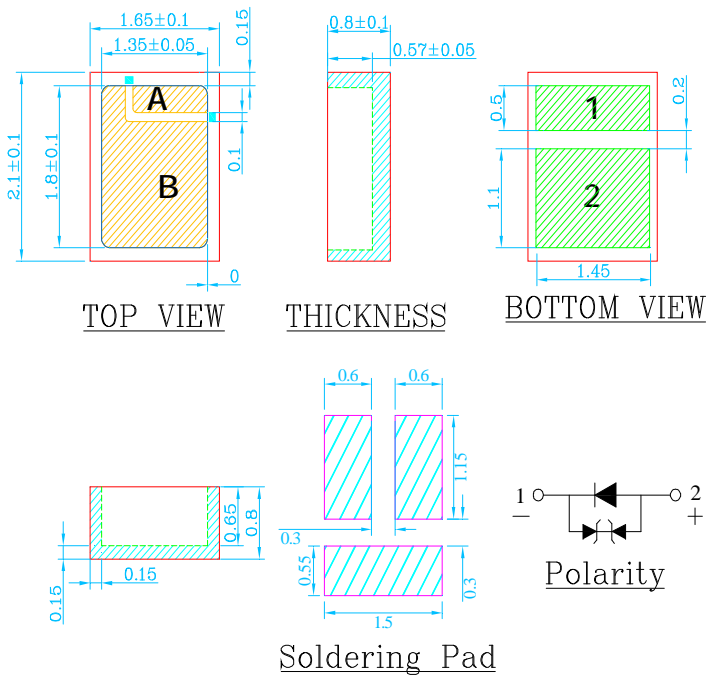
● Features:

1. Emitted Color: Pure White.
CCT:5000-6300K
2. Lens Appearance: Yellow diffuse.
3. 2.1x1.65x0.8mm standard package.
4. Suitable for all SMT assembly methods.
5. Compatible with infrared and vapor phase reflow solder process.
6. Compatible with automatic placement equipment.
7. This product doesn't contain restriction Substance, comply ROHS standard.

● Applications:

1. Mobile phone Camera Flash(Camera flash light/strobe light for mobile devices)
2. Torch light for DV(Digital Video)application.
3. Indoor lighting applications.
4. Signal and symbol luminaries for orientation Maker lights.
5. TFT backlighting.
6. Exterior and interior illumination applications
7. Decorative and Entertainment Lighting.
8. Exterior and interior automotive illumination..

● Package Dimensions:



NOTES:

1. Substrate Material: ceramic(WHITE).
2. Substrate Material Thickness: 0.8mm

● Absolute Maximum Ratings(Ta=25°C)

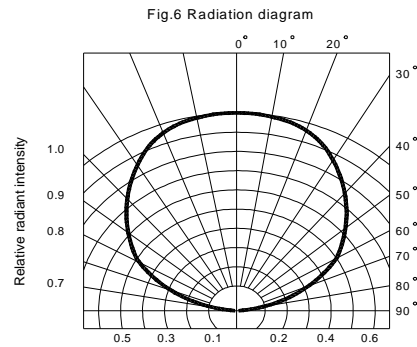
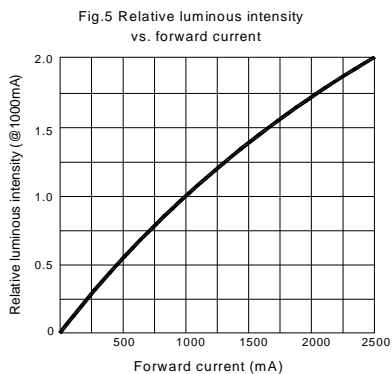
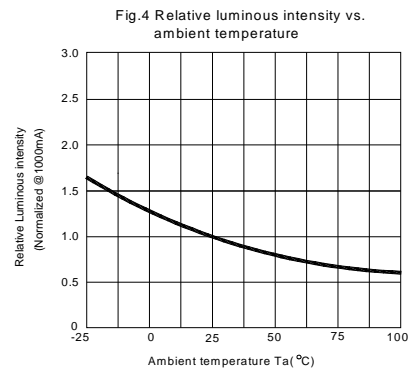
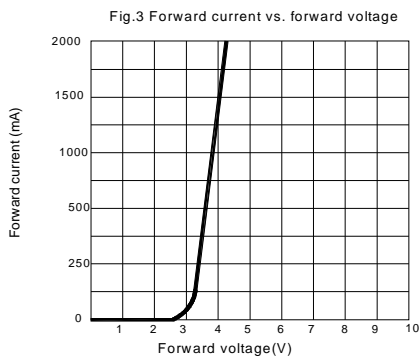
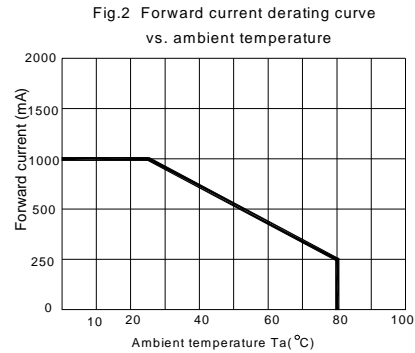
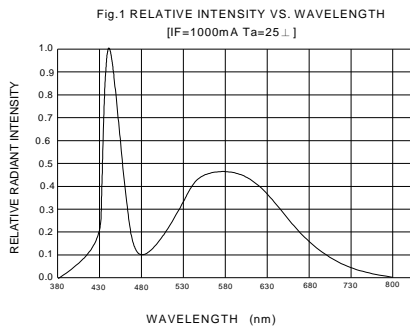
Parameter	Symbol	Rating	Unit
Power Dissipation	P _d	4000	mW
Forward Current	I _F	1000	mA
Peak Forward Current*1 (400ms:ON, 3600ms:OFF)	I _{FP}	2000	mA
Reverse Voltage	V _R	5	V
Operating Temperature	T _{opr}	-40°C ~85°C	-
Storage Temperature	T _{stg}	-40°C ~100°C	-
Soldering Temperature	T _{sol}	See Page 7	-

*1 Condition for I_{FP} is pulse of 1/10 duty and 400msec width.

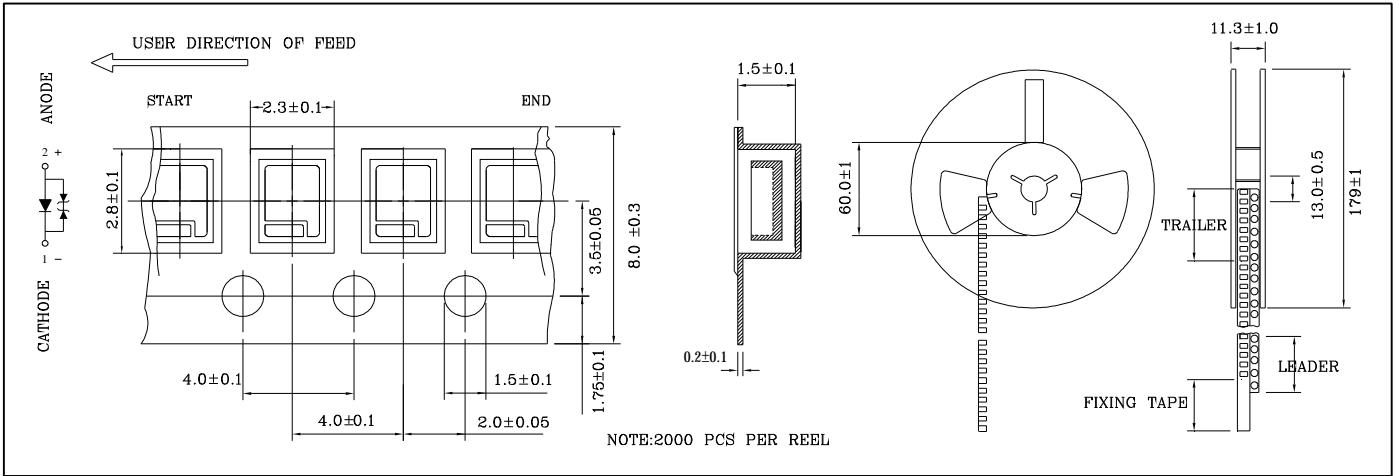
● Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V _f	I _F =1000mA	3.4	3.7	4.2	V
Luminous Intensity	I _v	I _F =1000mA	160	-	-	lm
Chromaticity Coordinates	x	I _F =1000mA	-	0.33	-	-
	y	I _F =1000mA	-	0.34	-	
Reverse Current	I _R	V _R =5V	-	-	10	μA
Viewing Angle	2θ _{1/2}	I _F =1000mA	-	120	-	deg

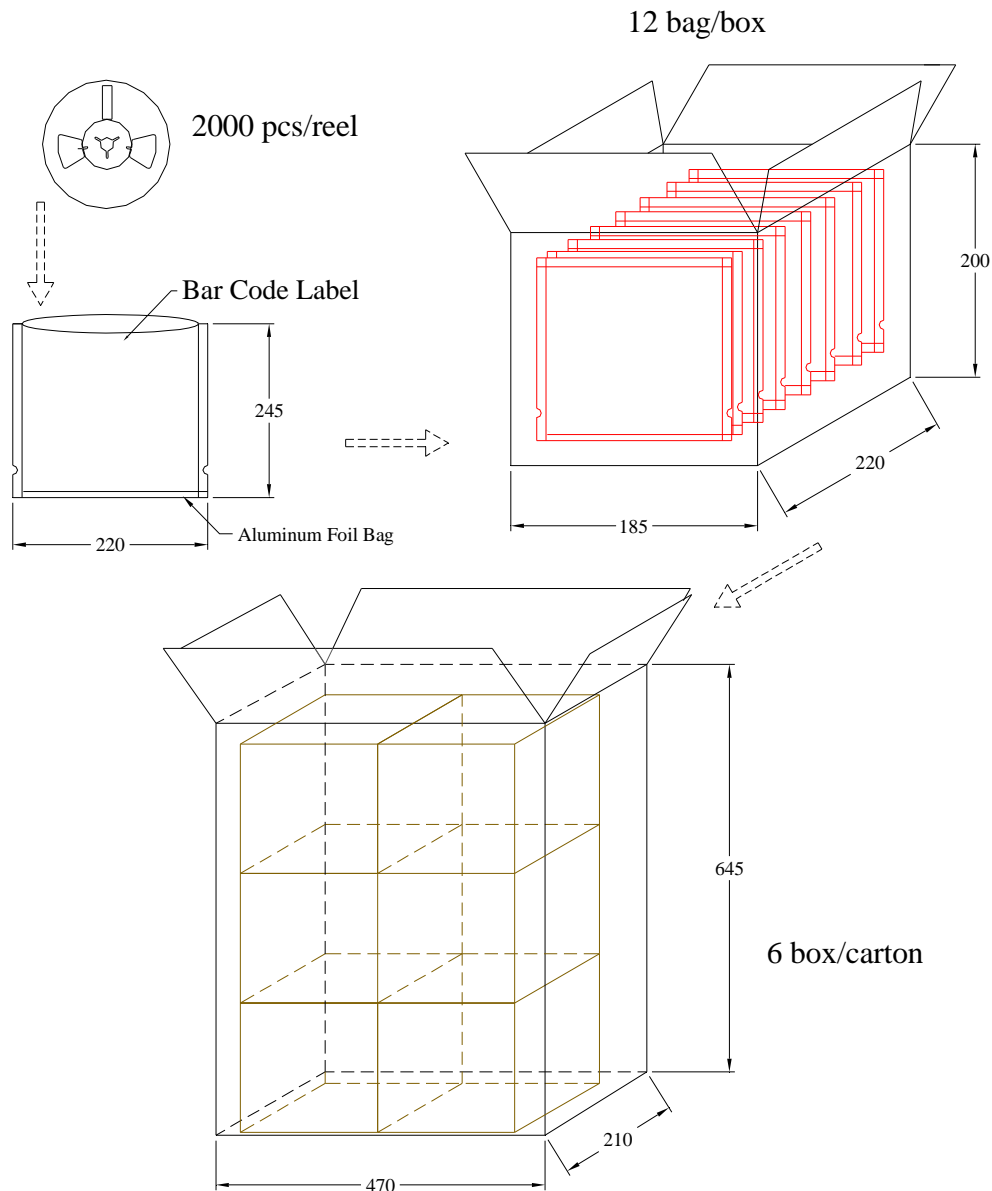
● Typical Electro-Optical Characteristics Curves



● Tapping and packaging specifications(Units: mm)



● Package Method:(unit:mm)



● Bin Limits

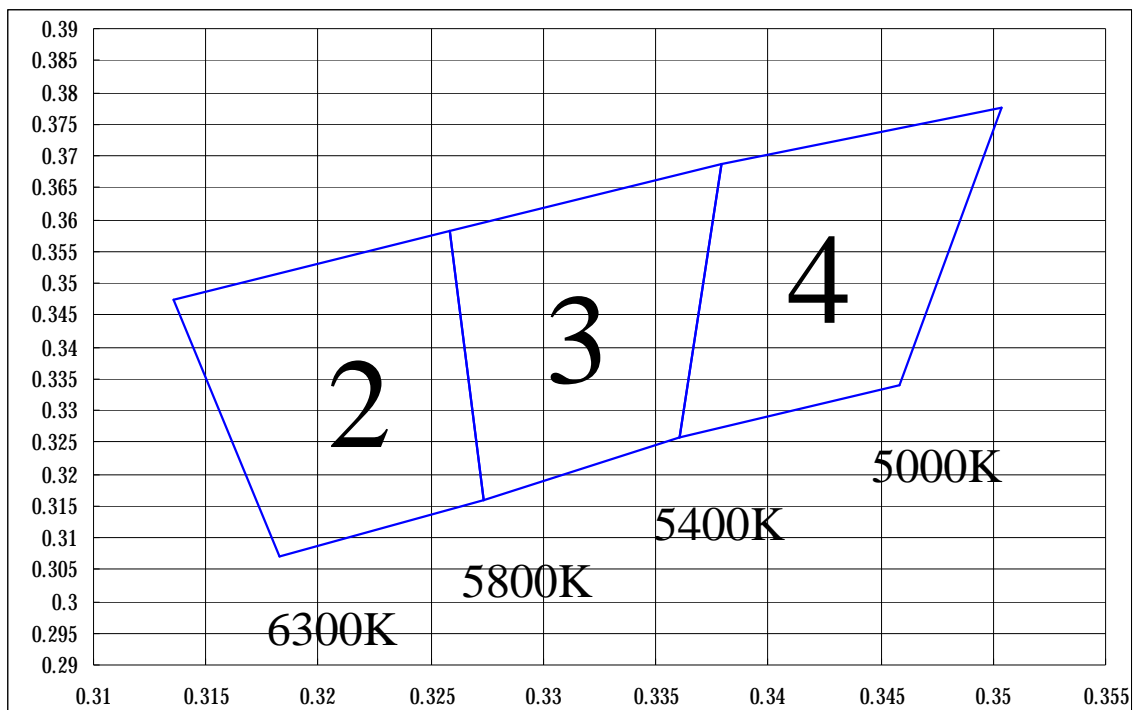
Intensity Bin Limits (At 1000mA)

BIN CODE	Min. (lm)	Max. (lm)
A6	160	170
A7	170	180
A8	180	190
A9	190	200
B1	200	210
B2	210	220

VF Bin Limits (At 1000mA)

BIN CODE	Min.(v)	Max.(v)
K	3.4	3.6
L	3.6	3.8
M	3.8	4.0
N	4.0	4.2

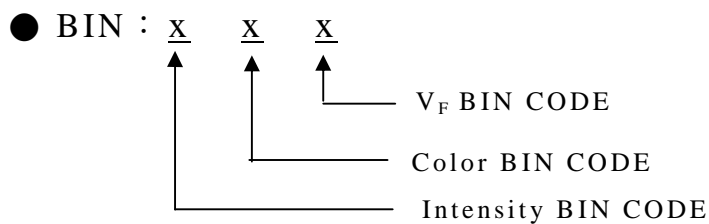
Color Bin Limits (At 1000mA)



Color Bin Limits (At 1000mA)

CCT	BIN	Chromaticity Coordinates				
		x	y	z	w	
5800-6300K	2	x	0.3273	0.3183	0.3136	0.3258
		y	0.3160	0.3072	0.3475	0.3583
5400-5800K	3	x	0.3361	0.3273	0.3258	0.3379
		y	0.3256	0.3160	0.3583	0.3688
5000-5400K	4	x	0.3459	0.3361	0.3379	0.3504
		y	0.3338	0.3256	0.3688	0.3775

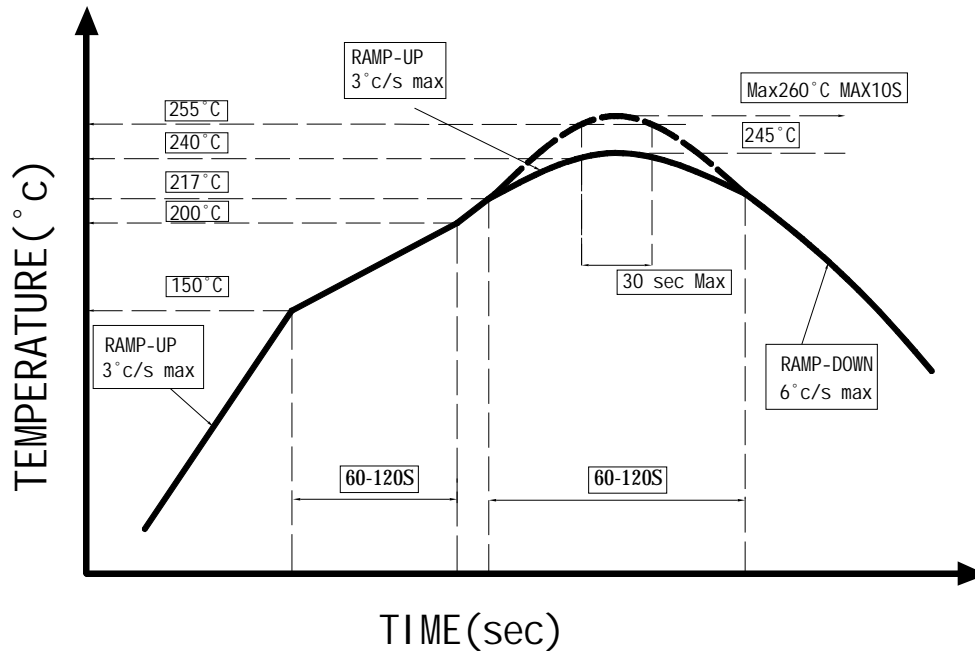
CCT : Tolerance for each Bin limit is $\pm 100K$



Notes:

1. I_v : Tolerance for each Bin limit is $\pm 10 \%$
2. Color : Tolerance for each Bin limit is ± 0.005
3. Bin categories are established for classification of products.
Products may not be available in all bin categories.

●IR-Reflow



- 1、 Avoid any external stress applied to the resin while the LEDs are at high temperature, especially during soldering.
- 2、 Avoid rapid cooling or any excess vibration during temperature ramp-down process
- 3、 Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

●IRON Soldering

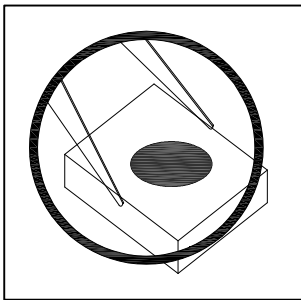
300°C Within 3 sec, one time only.

Handling Precautions

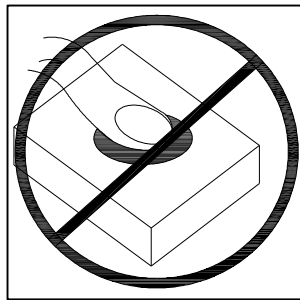
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

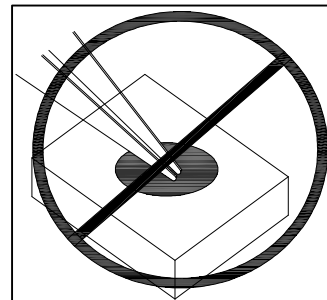
1. Handle the component along the side surfaces by using forceps or appropriate tools. (pic.1)
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry. (pic.2, pic.3)
3. Do not stack together assembled PCBs, containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry. (pic.4)
4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible. (pic.5)
5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup. (pic.5)
6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production. (pic.5)



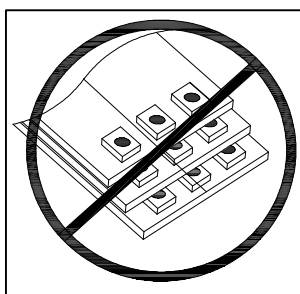
Pic.1



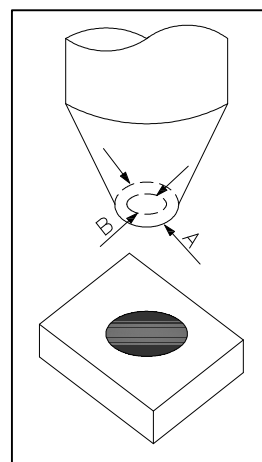
Pic.2



Pic.3



Pic.4



Pic.5



SINCE 1981

BRIGHT LED ELECTRONICS CORP.

BZ-HZS32B-P-S

● Notes for designing:

Care must be taken to provide the current limiting resistor in the circuit so as to drive the LEDs within the rated figures. Also, caution should be taken not to overload LEDs with instantaneous voltage at the turning ON and OFF of the circuit.

When using the pulse drive care must be taken to keep the average current within the rated figures. Also, the circuit should be designed so as to be subjected to reverse voltage when turning off the LEDs.

● Storage:

In order to avoid the absorption of moisture, it is recommended to solder LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature : 5°C-30°C(41°F) Humidity : RH 60% Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
 - a. Completed within 168 hours.
 - b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if:
 - 2a or 2b is not met.
- (4) If baking is required, devices must be baked under below conditions:
 - 48 hours at 60°C±3°C.

● Package and Label of Products:

- (1) Package: Products are packed in one bag of 2000 pcs (one taping reel) and a label is attached to each bag.
- (2) Label:

